

High Speed, High Voltage, High Side Gate Driver

FEATURES

- Wide Operating V_{IN} Range: Up to 60V
- Rugged Architecture Tolerant of 80V V_{IN} Transients
- Powerful 1.85Ω Driver Pull-Down (with 6V Supply)
- Powerful 1.1A Peak Current Driver Pull-Up (with 6V Supply)
- 7ns Fall Time Driving 1000pF Load
- 10ns Rise Time Driving 1000pF Load
- Drives Standard Threshold MOSFETs
- TTL/CMOS Compatible Inputs with Hysteresis
- Input Thresholds are Independent of Supply
- Undervoltage Lockout
- Low Profile (1mm) SOT-23 (ThinSOT™) and Thermally Enhanced 8-Pin MSOP Packages

APPLICATIONS

- Telecommunications Power Systems
- Distributed Power Architectures
- Server Power Supplies
- High Density Power Modules
- General Purpose Low-Side Driver

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DESCRIPTION

The **LTC®4440-5** is a high frequency high side N-channel MOSFET gate driver that is designed to operate in applications with V_{IN} voltages up to 60V. The LTC4440-5 can also withstand and continue to function during 80V V_{IN} transients. The powerful driver capability reduces switching losses in MOSFETs with high gate capacitances. The LTC4440-5's pull-up has a peak output current of 1.1A and its pull-down has an output impedance of 1.85Ω .

The LTC4440-5 features supply independent TTL/CMOS compatible input thresholds with 350mV of hysteresis. The input logic signal is internally level-shifted to the bootstrapped supply, which may function at up to 95V above ground.

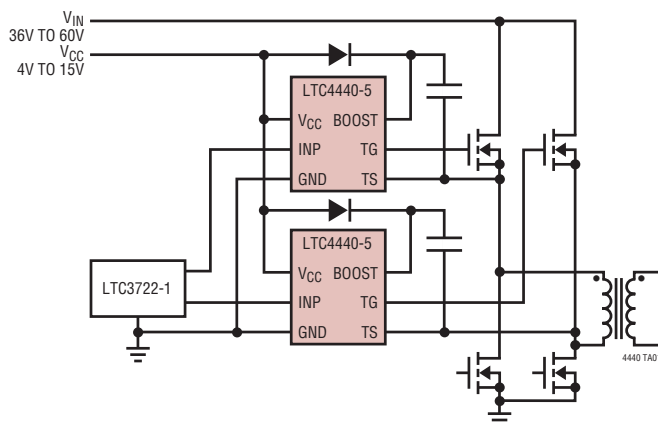
The LTC4440-5 is optimized for driving (5V) logic level FETs and contains an undervoltage lockout circuit that disables the external MOSFET when activated.

The LTC4440-5 is available in the low profile (1mm) SOT-23 or a thermally enhanced 8-lead MSOP package.

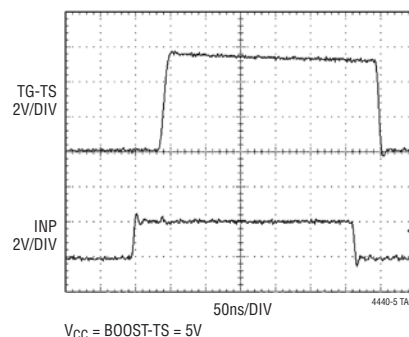
PARAMETER	LTC4440-5	LTC4440A-5	LTC4440
Max Operating TS	60V	80V	80V
Absolute Max TS	80V	100V	100V
MOSFET Gate Drive	4V to 15V	4V to 15V	8V to 15V
V_{CC} UV ⁺	3.2V	3.2V	6.3V
V_{CC} UV ⁻	3.04V	3.04V	6.0V

TYPICAL APPLICATION

Synchronous Phase-Modulated Full-Bridge Converter



LTC4440-5 Driving a 1000pF Capacitive Load



ABSOLUTE MAXIMUM RATINGS (Note 1)

Supply Voltage		TS Voltage (100ms)	–5V to 80V
V_{CC}	–0.3V to 15V	Peak Output Current < 1 μ s (TG)	4A
BOOST – TS	–0.3V to 15V	Operating Ambient Temperature Range	
INP Voltage	–0.3V to 15V	(Note 2)	–40°C to 85°C
BOOST Voltage (Continuous)	–0.3V to 85V	Junction Temperature (Note 3)	125°C
BOOST Voltage (100ms)	–0.3V to 95V	Storage Temperature Range	–65°C to 150°C
TS Voltage (Continuous)	–5V to 70V	Lead Temperature (Soldering, 10 sec)	300°C

PIN CONFIGURATION

TOP VIEW MS8E PACKAGE 8-LEAD PLASTIC MSOP $T_{JMAX} = 125^{\circ}\text{C}$, $\theta_{JA} = 40^{\circ}\text{C/W}$ EXPOSED PAD (PIN 9) IS GND, MUST BE SOLDERED TO PCB	TOP VIEW S6 PACKAGE 6-LEAD PLASTIC SOT-23 $T_{JMAX} = 125^{\circ}\text{C}$, $\theta_{JA} = 230^{\circ}\text{C/W}$
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ORDER INFORMATION

LEAD FREE FINISH	TAPE AND REEL	PART MARKING	PACKAGE DESCRIPTION	TEMPERATURE RANGE
LTC4440EMS8E-5#PBF	LTC4440EMS8E-5#TRPBF	LTBRG	8-Lead Plastic MSOP	–40°C to 85°C
LTC4440ES6-5#PBF	LTC4440ES6-5#TRPBF	LTBRF	6-Lead Plastic SOT-23	–40°C to 85°C

Consult LTC Marketing for parts specified with wider operating temperature ranges.

Consult LTC Marketing for information on nonstandard lead based finish parts.

For more information on lead free part marking, go to: <http://www.linear.com/leadfree/>

For more information on tape and reel specifications, go to: <http://www.linear.com/tapeandreel/>

ELECTRICAL CHARACTERISTICS

The ● denotes specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^{\circ}\text{C}$. $V_{CC} = V_{BOOST} = 6\text{V}$, $V_{TS} = \text{GND} = 0\text{V}$, unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Main Supply (V_{CC})						
I_{VCC}	DC Supply Current Normal Operation UVLO	INP = 0V $V_{CC} < \text{UVLO Threshold (Falling)} - 0.1\text{V}$		200 18	325 40	μA μA
UVLO	Undervoltage Lockout Threshold	V_{CC} Rising V_{CC} Falling Hysteresis	● 2.75 ● 2.60	3.20 3.04	3.65 3.50	V mV
Bootstrapped Supply (BOOST – TS)						
I_{BOOST}	DC Supply Current Normal Operation	INP = 0V INP = 6V		0 310	450	μA μA

ELECTRICAL CHARACTERISTICS

The ● denotes specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^\circ\text{C}$. $V_{CC} = V_{BOOST} = 6\text{V}$, $V_{TS} = 0\text{V}$, unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Input Signal (INP)							
V_{IH}	High Input Threshold	INP Ramping High	●	1.2	1.6	2	V
V_{IL}	Low Input Threshold	INP Ramping Low	●	0.8	1.25	1.6	V
$V_{IH} - V_{IL}$	Input Voltage Hysteresis				0.350		V
I_{INP}	Input Pin Bias Current				± 0.01	± 2	μA
Output Gate Driver (TG)							
V_{OH}	High Output Voltage	$I_{TG} = -10\text{mA}$, $V_{OH} = V_{BOOST} - V_{TG}$			0.7		V
V_{OL}	Low Output Voltage	$I_{TG} = 100\text{mA}$	●		185	275	mV
I_{PU}	Peak Pull-Up Current		●	0.75	1.1		A
R_{DS}	Output Pull-Down Resistance		●		1.85	2.75	Ω
Switching Timing							
t_r	Output Rise Time	10% – 90%, $C_L = 1\text{nF}$ 10% – 90%, $C_L = 10\text{nF}$			10 100		ns ns
t_f	Output Fall Time	10% – 90%, $C_L = 1\text{nF}$ 10% – 90%, $C_L = 10\text{nF}$			7 70		ns ns
t_{PLH}	Output Low-High Propagation Delay		●		35	65	ns
t_{PHL}	Output High-Low Propagation Delay		●		33	65	ns

Note 1: Absolute Maximum Ratings are those values beyond which the life of a device may be impaired.

Note 2: The LTC4440-5 is guaranteed to meet performance specifications from 0°C to 85°C . Specifications over the -40°C to 85°C operating temperature range are assured by design, characterization and correlation with statistical process controls.

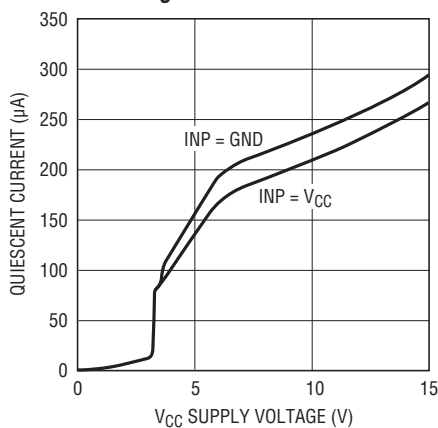
Note 3: T_J is calculated from the ambient temperature T_A and power dissipation PD according to the following formula:

$$T_J = T_A + (PD \cdot \theta_{JA}^\circ\text{C/W})$$

Note 4: Failure to solder the exposed back side of the MS8E package to the PC board will result in a thermal resistance much higher than 40°C/W .

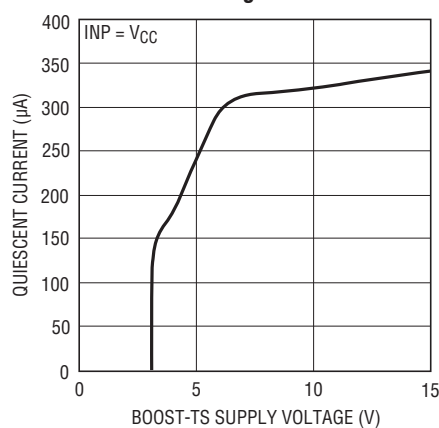
TYPICAL PERFORMANCE CHARACTERISTICS

V_{CC} Supply Quiescent Current vs Voltage



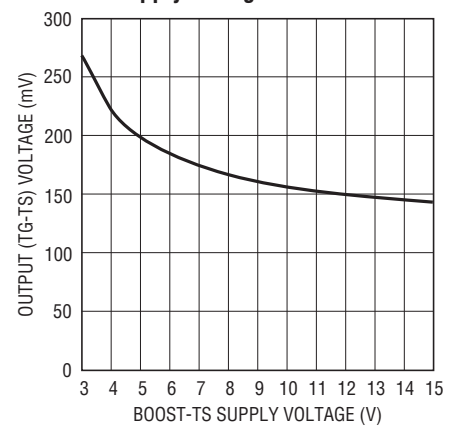
4440-5 G01

BOOST-TS Supply Quiescent Current vs Voltage



4440-5 G02

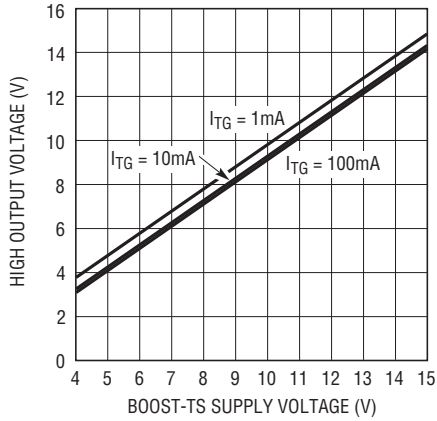
Output Low Voltage (V_{OL}) vs Supply Voltage



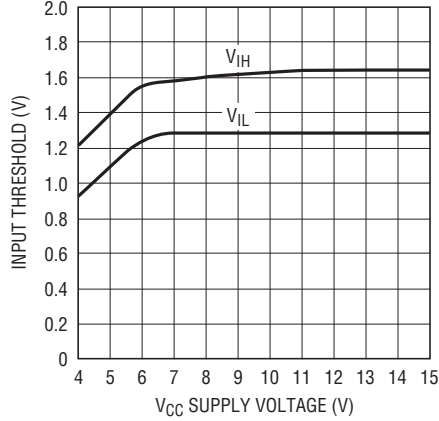
4440-5 G03

TYPICAL PERFORMANCE CHARACTERISTICS

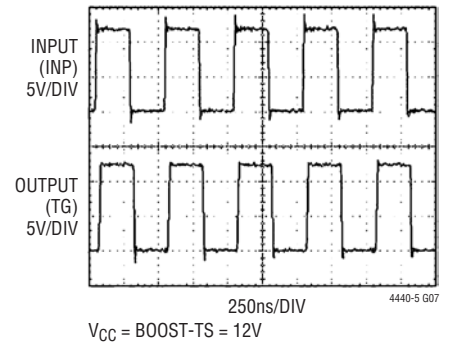
Output High Voltage (V_{OH}) vs Supply Voltage



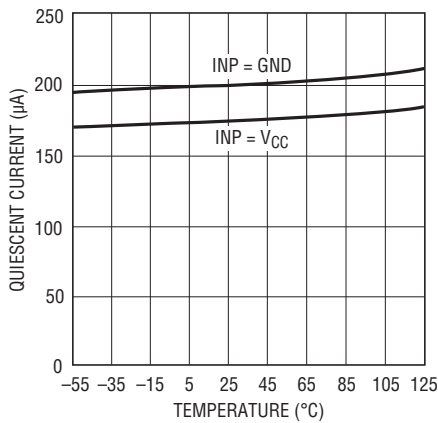
Input (INP) Thresholds vs Supply Voltage



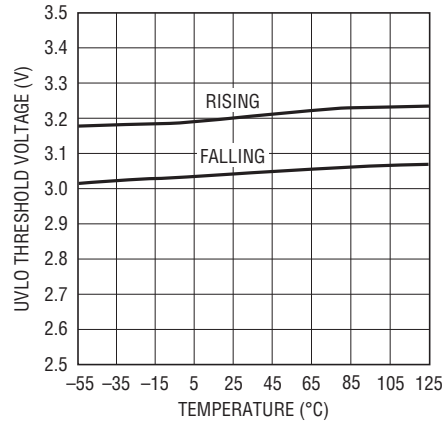
2MHz Operation



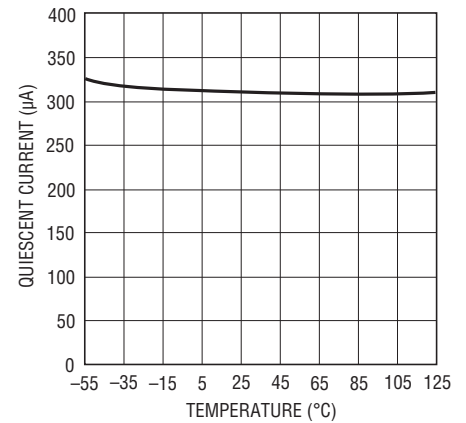
V_{CC} Supply Current vs Temperature



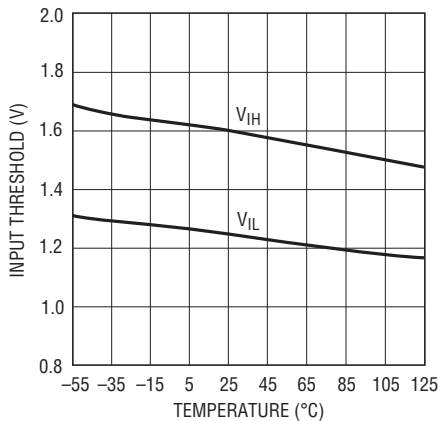
V_{CC} Undervoltage Lockout Thresholds vs Temperature



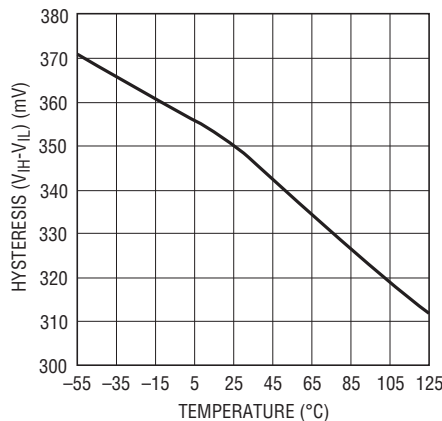
BOOST-TS Quiescent Current vs Temperature



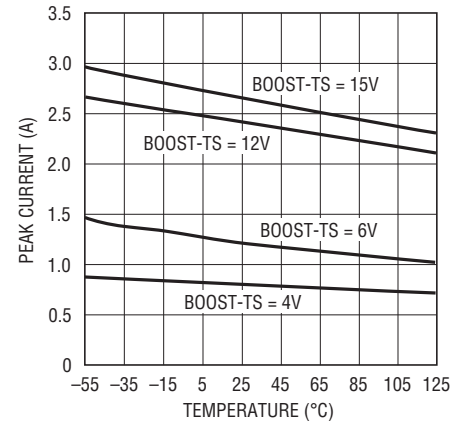
Input (INP) Threshold vs Temperature



Input Threshold Hysteresis vs Temperature

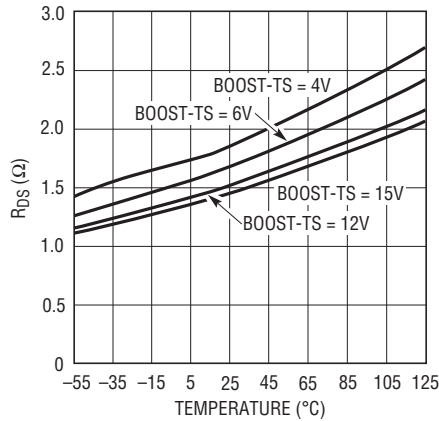


Peak Driver (TG) Pull-Up Current vs Temperature

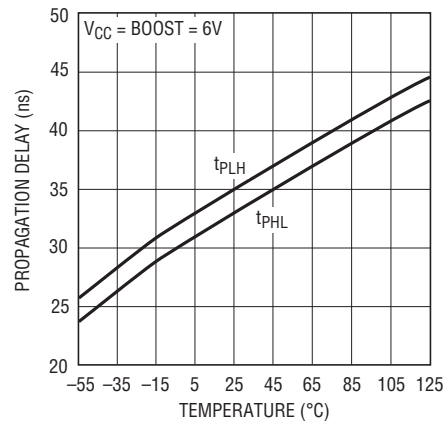


TYPICAL PERFORMANCE CHARACTERISTICS

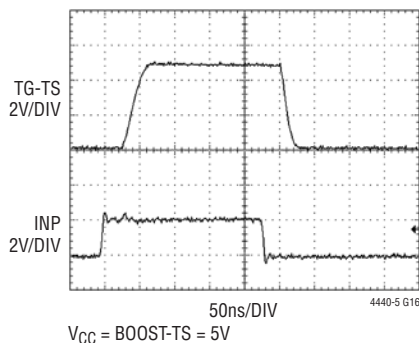
Output Driver Pull-Down Resistance vs Temperature



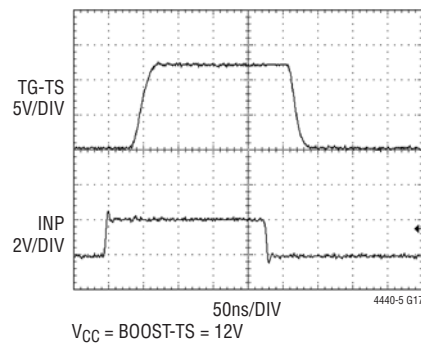
Propagation Delay vs Temperature



Driving a 3300pF Capacitive Load



Driving a 3300pF Capacitive Load



PIN FUNCTIONS

SOT-23 Package

V_{CC} (Pin 1): Chip Supply. This pin powers the internal low side circuitry. A low ESR ceramic bypass capacitor should be tied between this pin and the GND pin (Pin 2).

GND (Pin 2): Chip Ground.

INP (Pin 3): Input Signal. TTL/CMOS compatible input referenced to GND (Pin 2).

TS (Pin 4): Top (High Side) source connection or GND if used in ground referenced applications.

TG (Pin 5): High Current Gate Driver Output (Top Gate). This pin swings between TS and BOOST.

BOOST (Pin 6): High Side Bootstrapped Supply. An external capacitor should be tied between this pin and TS (Pin 4). Normally, a bootstrap diode is connected between V_{CC} (Pin 1) and this pin. Voltage swing at this pin is from V_{CC} - V_D to V_{IN} + V_{CC} - V_D, where V_D is the forward voltage drop of the bootstrap diode.

PIN FUNCTIONS

Exposed Pad MS8E Package

INP (Pin 1): Input Signal. TTL/CMOS compatible input referenced to GND (Pin 2).

GND (Pins 2, 4): Chip Ground.

V_{CC} (Pin 3): Chip Supply. This pin powers the internal low side circuitry. A low ESR ceramic bypass capacitor should be tied between this pin and the GND pin (Pin 2).

NC (Pin 5): No Connect. No connection required. For convenience, this pin may be tied to Pin 6 (BOOST) on the application board.

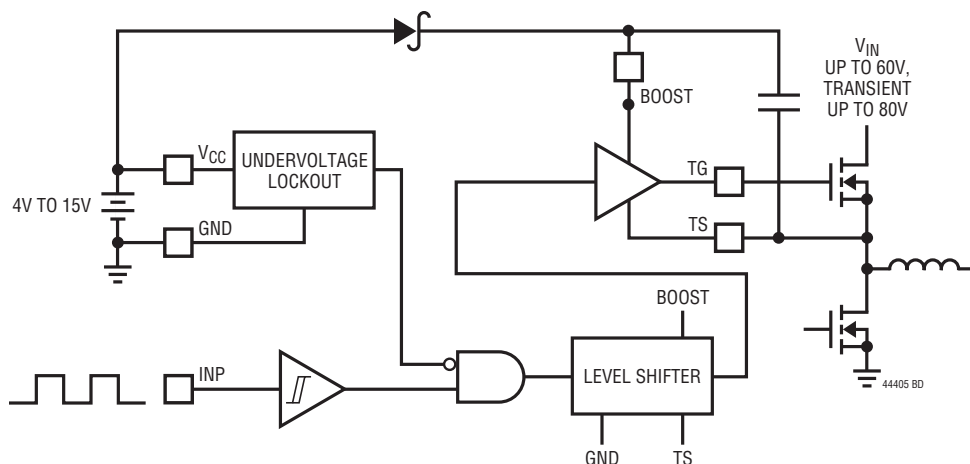
BOOST (Pin 6): High Side Bootstrapped Supply. An external capacitor should be tied between this pin and TS (Pin 8). Normally, a bootstrap diode is connected between V_{CC} (Pin 3) and this pin. Voltage swing at this pin is from V_{CC} – V_D to V_{IN} + V_{CC} – V_D, where V_D is the forward voltage drop of the bootstrap diode.

TG (Pin 7): High Current Gate Driver Output (Top Gate). This pin swings between TS and BOOST.

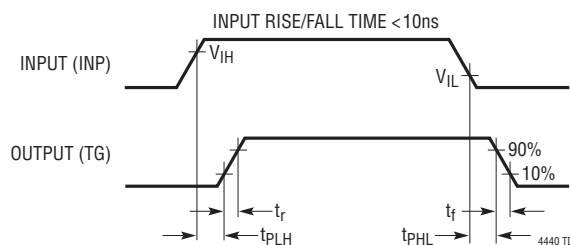
TS (Pin 8): Top (High Side) source connection or GND if used in ground referenced applications.

Exposed Pad (Pin 9): Ground. Must be electrically connected to Pins 2 and 4 and soldered to PCB ground for optimum thermal performance.

BLOCK DIAGRAM



TIMING DIAGRAM



APPLICATIONS INFORMATION

Power Dissipation

To ensure proper operation and long-term reliability, the LTC4440-5 must not operate beyond its maximum temperature rating. Package junction temperature can be calculated by:

$$T_J = T_A + PD (\theta_{JA})$$

where:

T_J = Junction Temperature

T_A = Ambient Temperature

PD = Power Dissipation

θ_{JA} = Junction-to-Ambient Thermal Resistance

Power dissipation consists of standby and switching power losses:

$$PD = P_{STDBY} + P_{AC}$$

where:

P_{STDBY} = Standby Power Losses

P_{AC} = AC Switching Losses

The LTC4440-5 consumes very little current during standby. The DC power loss at $V_{CC} = 6V$ and $V_{BOOST-TS} = 6V$ is only $(200\mu A)(6V) = 1.2mW$ with $INP = 0V$.

AC switching losses are made up of the output capacitive load losses and the transition state losses. The capacitive load losses are primarily due to the large AC currents needed to charge and discharge the load capacitance during switching. Load losses for the output driver driving a pure capacitive load C_{OUT} would be:

$$\text{Load Capacitive Power} = (C_{OUT})(f)(V_{BOOST-TS})^2$$

The power MOSFET's gate capacitance seen by the driver output varies with its V_{GS} voltage level during switching. A power MOSFET's capacitive load power dissipation can be calculated using its gate charge, Q_G . The Q_G value corresponding to the MOSFET's V_{GS} value (V_{CC} in this case) can be readily obtained from the manufacturer's Q_G vs V_{GS} curves:

$$\text{Load Capacitive Power (MOS)} = (V_{BOOST-TS})(Q_G)(f)$$

Transition state power losses are due to both AC currents required to charge and discharge the driver's internal

nodal capacitances and cross-conduction currents in the internal gates.

Undervoltage Lockout (UVLO)

The LTC4440-5 contains an undervoltage lockout detector that monitors V_{CC} . When V_{CC} falls below 3.04V, the internal buffer is disabled and the output pin TG is pulled down to TS.

Bypassing and Grounding

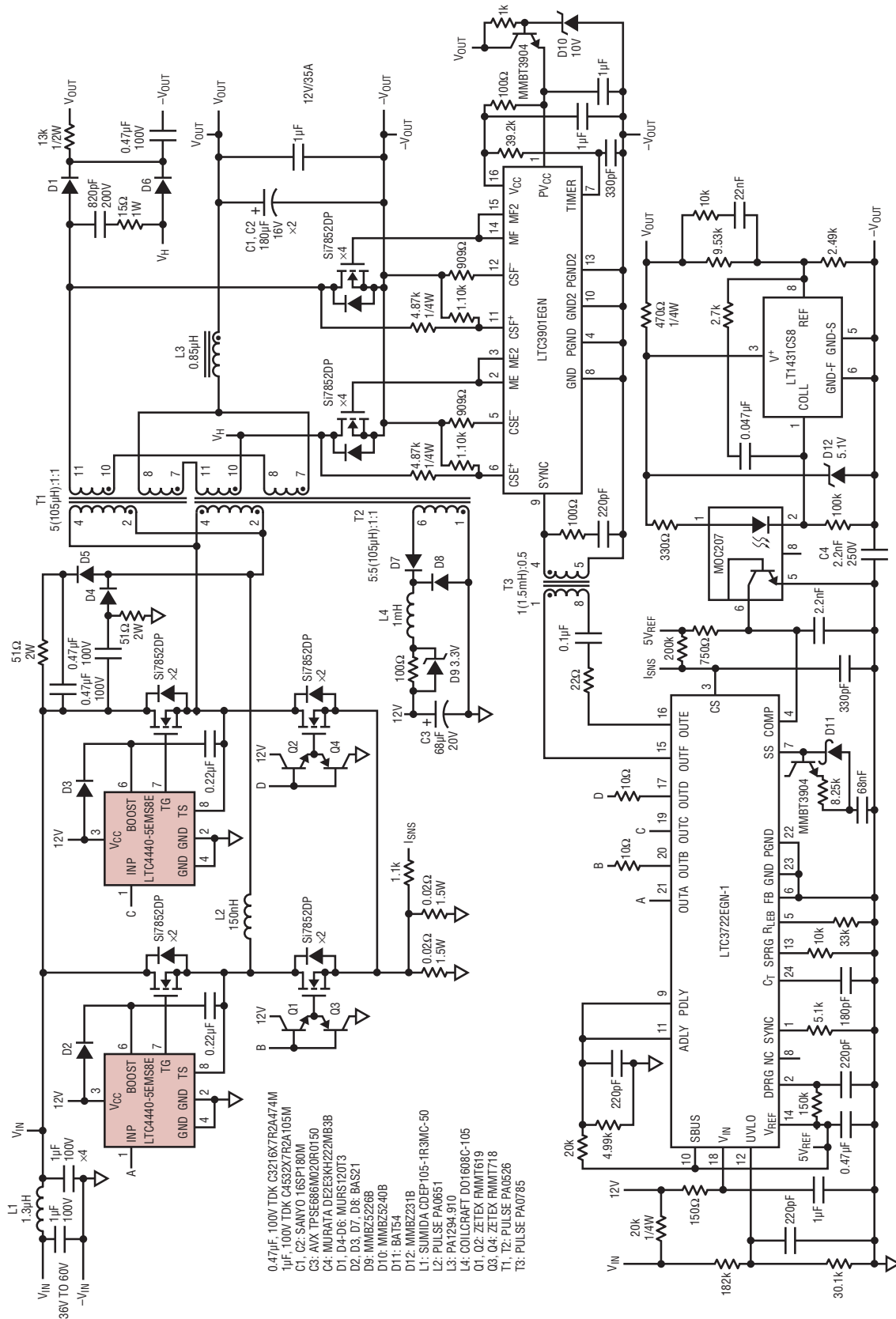
The LTC4440-5 requires proper bypassing on the V_{CC} and $V_{BOOST-TS}$ supplies due to its high speed switching (nanoseconds) and large AC currents (Amperes). Careless component placement and PCB trace routing may cause excessive ringing and under/overshoot.

To obtain the optimum performance from the LTC4440-5:

- Mount the bypass capacitors as close as possible between the V_{CC} and GND pins and the BOOST and TS pins. The leads should be shortened as much as possible to reduce lead inductance.
- Use a low inductance, low impedance ground plane to reduce any ground drop and stray capacitance. Remember that the LTC4440-5 switches >2A peak currents and any significant ground drop will degrade signal integrity.
- Plan the power/ground routing carefully. Know where the large load switching current is coming from and going to. Maintain separate ground return paths for the input pin and the output power stage.
- Keep the copper trace between the driver output pin and the load short and wide.
- When using the MS8E package, be sure to solder the exposed pad on the back side of the LTC4440-5 package to the board. Correctly soldered to a 2500mm² double-sided 1oz copper board, the LTC4440-5 has a thermal resistance of approximately 40°C/W. Failure to make good thermal contact between the exposed back side and the copper board will result in thermal resistances far greater than 40°C/W.

TYPICAL APPLICATIONS

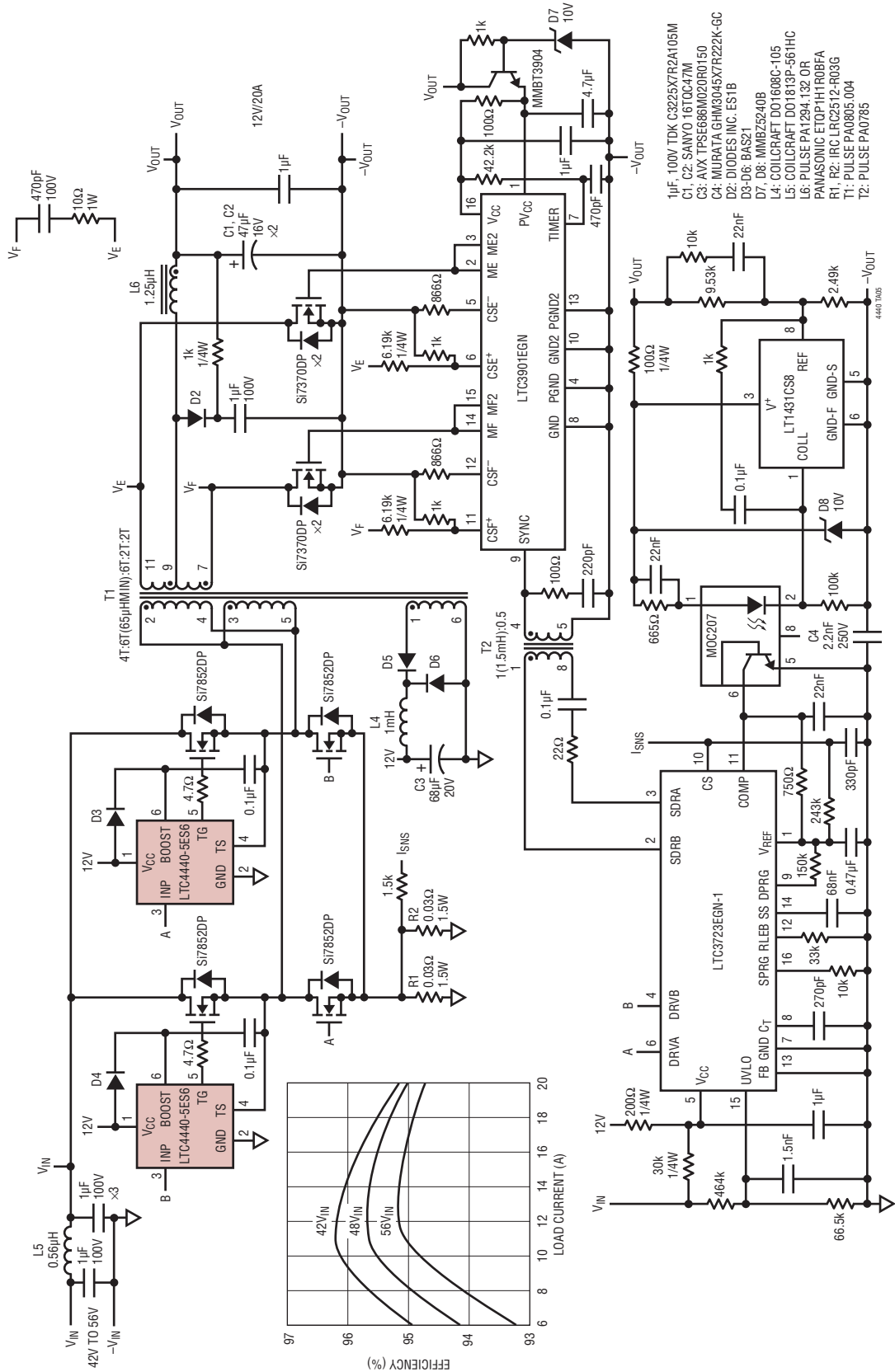
LTC3722/LTC4440-5 420W 36V-60VIN to 12V/35A Isolated Full-Bridge Supply



44405fb

TYPICAL APPLICATIONS

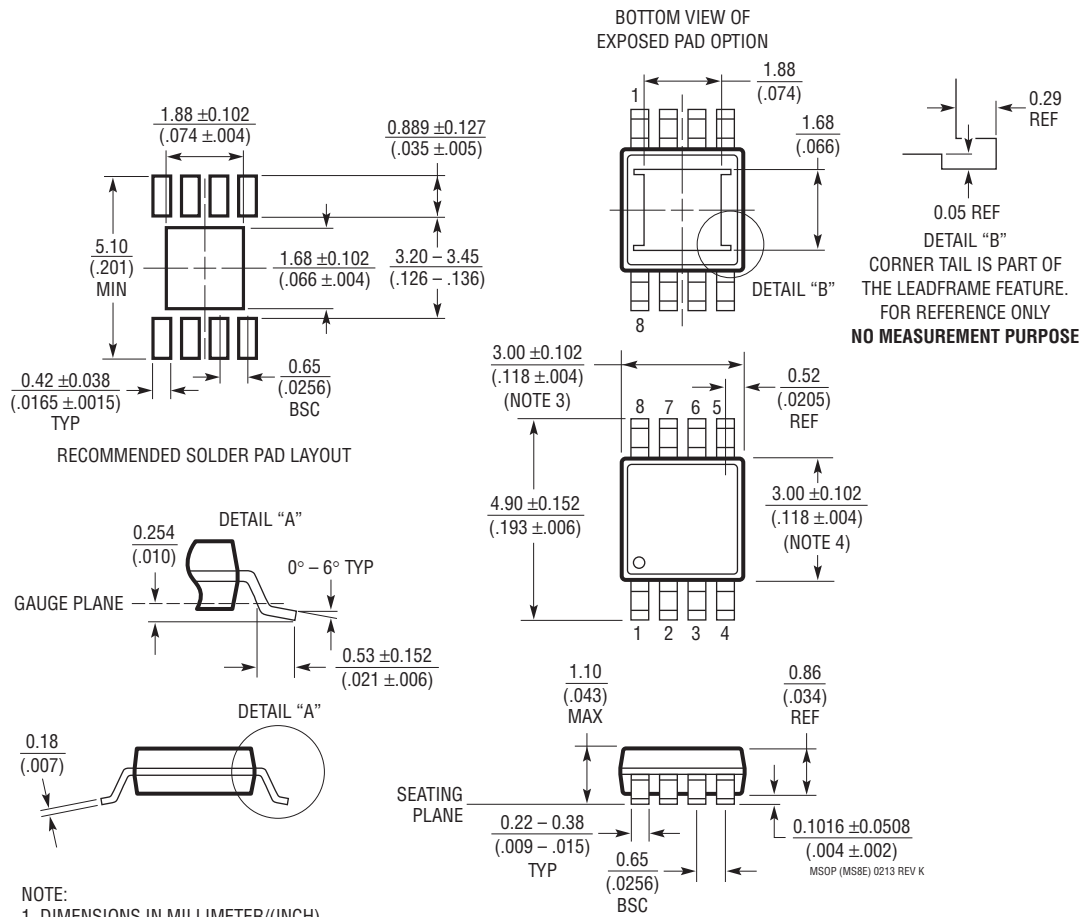
LTC3723-1 240W 42-56V_{IN} to 12V/20A Isolated 1/4Brick (2.3" × 1.45")



PACKAGE DESCRIPTION

Please refer to <http://www.linear.com/designtools/packaging/> for the most recent package drawings.

MS8E Package 8-Lead Plastic MSOP, Exposed Die Pad (Reference LTC DWG # 05-08-1662 Rev K)



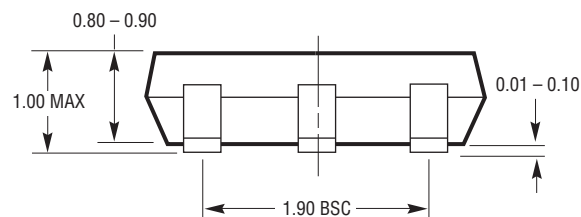
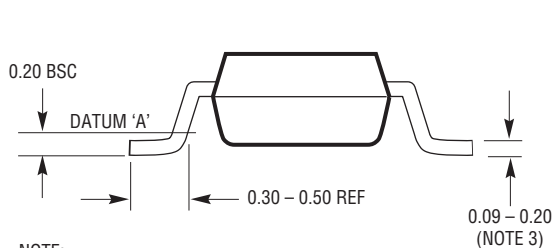
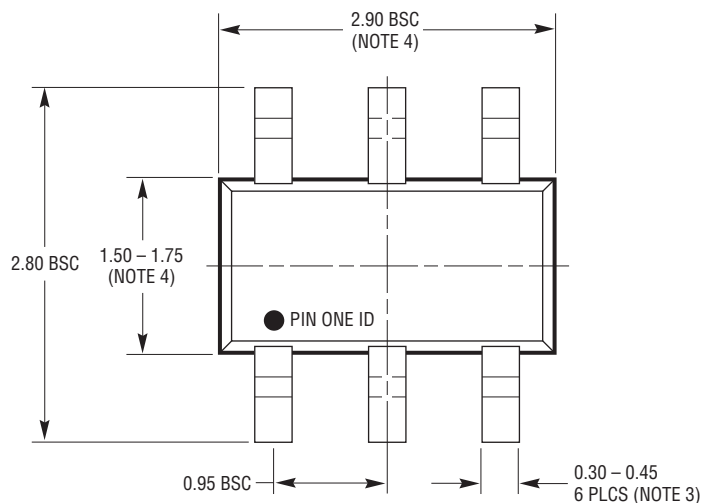
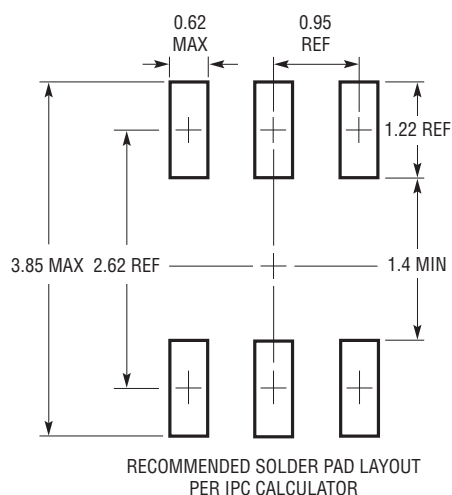
NOTE:

1. DIMENSIONS IN MILLIMETER/(INCH)
2. DRAWING NOT TO SCALE
3. DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.152mm ($.006$) PER SIDE
4. DIMENSION DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS.
INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.152mm ($.006$) PER SIDE
5. LEAD COPLANARITY (BOTTOM OF LEADS AFTER FORMING) SHALL BE 0.102mm ($.004$) MAX
6. EXPOSED PAD DIMENSION DOES INCLUDE MOLD FLASH. MOLD FLASH ON E-PAD SHALL NOT EXCEED 0.254mm ($.010$) PER SIDE.

PACKAGE DESCRIPTION

Please refer to <http://www.linear.com/designtools/packaging/> for the most recent package drawings.

S6 Package
6-Lead Plastic TSOT-23
 (Reference LTC DWG # 05-08-1636)



NOTE:

1. DIMENSIONS ARE IN MILLIMETERS
2. DRAWING NOT TO SCALE
3. DIMENSIONS ARE INCLUSIVE OF PLATING
4. DIMENSIONS ARE EXCLUSIVE OF MOLD FLASH AND METAL BURR
5. MOLD FLASH SHALL NOT EXCEED 0.254mm
6. JEDEC PACKAGE REFERENCE IS MO-193

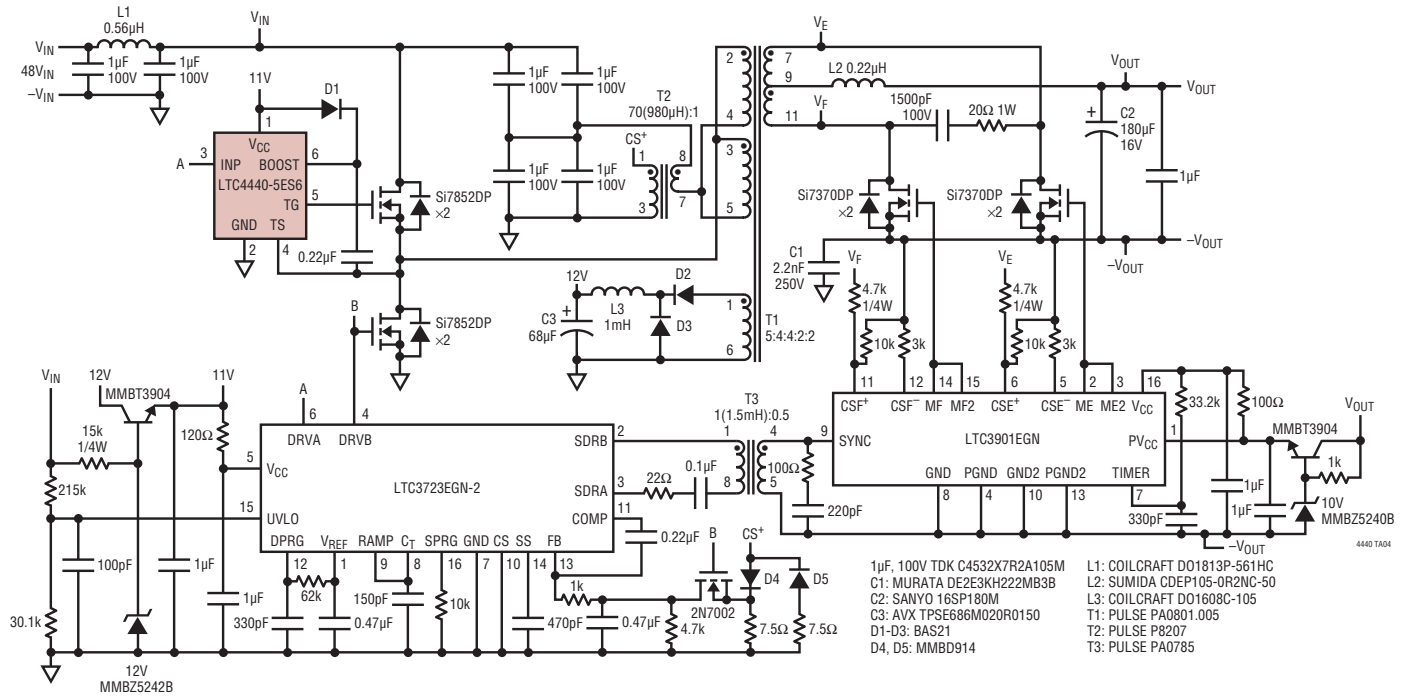
S6 TSOT-23 0302

REVISION HISTORY (Revision history begins at Rev B)

REV	DATE	DESCRIPTION	PAGE NUMBER
B	1013	Added comparison table	1

TYPICAL APPLICATION

240W 42V-56V_{IN} to Unregulated 12V Half-Bridge Converter



RELATED PARTS

PART NUMBER	DESCRIPTION	COMMENTS
LT[®]1161	Quad Protected High Side MOSFET Driver	8V to 48V Supply Range, $t_{ON} = 200\mu s$, $t_{OFF} = 28\mu s$
LTC1693 Family	High Speed Dual MOSFET Drivers	1.5A Peak Output Current, $4.5V \leq V_{IN} \leq 13.2V$
LT1952	Single Switch Synchronous Forward Controller	25W to 500W DC/DC Controller
LT3010/LT3010-5	50mA, 3V to 80V Low Dropout Micropower Regulators	Low Quiescent Current (30μA), Stable with Small (1μF) Ceramic Capacitor
LT3430	High Voltage, 3A, 200kHz Step-Down Switching Regulator	Input Voltages Up to 60V, Internal 0.1Ω Power Switch, Current Mode Architecture, 16-Pin Exposed Pad TSSOP Package
LTC3722-1/ LTC3722-2	Synchronous Dual Mode Phase Modulated Full-Bridge Controllers	Adaptive Zero Voltage Switching, High Output Power Levels (Up to Kilowatts)
LTC3723-1/ LTC3723-2	Synchronous Push-Pull PWM Controllers	Current Mode or Voltage Mode Push-Pull Controllers
LTC3900	Synchronous Rectifier Driver for Forward Converters	Programmable Time Out, Reverse Inductor Current Sense
LTC3901	Secondary Side Synchronous Driver for Push-Pull and Full-Bridge Converters	Programmable Time Out, Reverse Inductor Current Sense
LTC4440	High Speed, High Voltage, High Side Gate Driver	High Side Source up to 100V, 8V to 15V Gate Drive Supply, Undervoltage Lockout, 6-Lead ThinSOT or 8-Lead Exposed MSOP Package
LTC4441	6A MOSFET Driver	Adjustable Gate Drive from 5V to 8V, $5V \leq V_{IN} \leq 28V$